

Exhibit 1

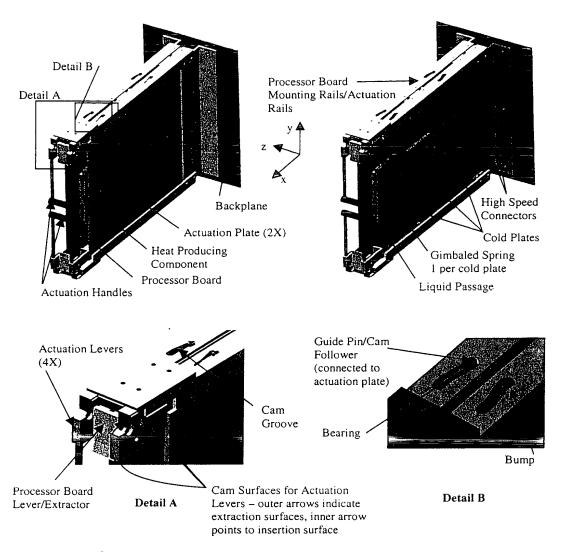


Figure 3. Mechanically Actuated Thermal Connector Assembly

Charles 2/19/6





Howlott-Packard Company 1501 Pago MA Road Mail Stop 4U-10 Palo Alto, CA 94304-1126 www.hp.com

Lloyd E. Dakin, Jr. PATENT ATTORNEY

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James R Brueggemann Sheppard Mullin Richter & Hampton LLP 333 S Hope St 48th Floor Los Angeles CA 90071 RECEIVED OCT 2 2 2003

TECHNOLOGY CENTER R3700

RE: Preparation of Patent Application

Redacted

HP Reference No.: 10005107.

Entitled: Mechanically Actuated Thermal Connector For Cooling Electronics

HP Required Date: February 22, 2001

Dear James:

We would like you to provide a quote of the cost for your firm to prepare a US Patent application based on the HP Invention Disclosure identified above, a copy of which is enclosed.

Redacted

Sincerely,

Lloyd E. Dakin, Jr.

Enc.: HP Invention Disclosure

RFQ

Outside Counsel Checklist

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OCT 27 2003

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